

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	103	438/22,106,110,111,112,121,123,124,617.ccls. and lead same (above overhang overl\$4 over) same (chip die ic) and (substrate board carrier) and wire and (encapsulant resin epoxy mold\$) and (chip die ic) with (die adj paddle flag mount\$3 adj member)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 18:09
L2	19	361/772-774,807,813.ccls. and lead same (above overhang overl\$4 over) same (chip die ic) and (substrate board carrier) and wire and (encapsulant resin epoxy mold\$) and (chip die ic) with (die adj paddle flag mount\$3 adj member)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 18:40
L3	51	257/692-696.ccls. and lead same (chip die ic) and (substrate board carrier) and wire and (encapsulant resin epoxy mold\$) and (chip die ic) with (die adj paddle flag mount\$3 adj member)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 19:00
L4	6	lead same (chip die ic) and (substrate board carrier) and wire and (encapsulant resin epoxy mold\$) and (chip die ic) same (die adj paddle flag mount\$3 adj member)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 18:46
L5	1556	lead same (chip die ic) and (substrate board carrier) and wire and (encapsulant resin epoxy mold\$) and (chip die ic)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 18:48
L6	337	"257"/\$.ccls. and lead same (chip die ic) and (substrate board carrier) and wire and (encapsulant resin epoxy mold\$) and (chip die ic)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 19:09
L7	78	"438"/\$.ccls. and lead same (chip die ic) and (substrate board carrier) and wire and (encapsulant resin epoxy mold\$) and (chip die ic)	EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 18:58
L8	148	"257"/\$.ccls. and LOC and (chip die ic) and (substrate board carrier) and wire and (encapsulant resin epoxy mold\$) and (chip die ic) and (die adj paddle flag mount\$3 adj member)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 19:05

L9	77	"438"/\$.ccls. and LOC and (chip die ic) and (substrate board carrier) and wire and (encapsulant resin epoxy mold\$) and (chip die ic) and (die adj paddle flag mount\$3 adj member)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 19:07
L10	10	"361"/\$.ccls. and LOC and (chip die ic) and (substrate board carrier) and wire and (encapsulant resin epoxy mold\$) and (chip die ic) and (die adj paddle flag mount\$3 adj member)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 19:07
L11	7978	"257"/\$.ccls. and lead same (chip die ic) and (substrate board carrier) and wire and (encapsulant resin epoxy mold\$) and (chip die ic)	USPAT	OR	ON	2005/10/24 19:10
L12	88590	"257"/\$.ccls. and wire lead and (encapsulant resin epoxy mold\$) and (chip die ic)	USPAT	OR	ON	2005/10/24 19:11
L13	10932	"257"/\$.ccls. and wire and lead and (encapsulant resin epoxy mold\$) and (chip die ic)	USPAT	OR	ON	2005/10/24 19:12
L14	7938	"257"/\$.ccls. and wire same lead and (encapsulant resin epoxy mold\$) and (chip die ic)	USPAT	OR	ON	2005/10/24 19:12
L15	6882	"257"/\$.ccls. and wire same lead and (encapsulant resin epoxy mold\$) same (chip die ic)	USPAT	OR	ON	2005/10/24 19:13
L16	6744	"257"/\$.ccls. and wire same lead same (chip die ic) and (encapsulant resin epoxy mold\$)	USPAT	OR	ON	2005/10/24 19:31
L17	4318	"257"/\$.ccls. and wire same lead same (chip die ic) same (encapsulant resin epoxy mold\$)	USPAT	OR	ON	2005/10/24 19:15
L18	238	"257"/\$.ccls. and wire same lead same (chip die ic) same (encapsulant resin epoxy mold\$) and MOSFET	USPAT	OR	ON	2005/10/24 19:26
L19	67	"438"/\$.ccls. and wire same lead same (chip die ic) same (encapsulant resin epoxy mold\$) and MOSFET	USPAT	OR	ON	2005/10/24 19:29
L20	22	"361"/\$.ccls. and wire same lead same (chip die ic) same (encapsulant resin epoxy mold\$) and MOSFET	USPAT	OR	ON	2005/10/24 19:29
L21	3566	"257"/\$.ccls. and wire same lead adj frame same (chip die ic) and (encapsulant resin epoxy mold\$)	USPAT	OR	ON	2005/10/24 19:33

L22	578	"257"/\$.ccls. and wire same lead adj frame same (chip die ic) and (encapsulant resin epoxy mold\$) and (flag die adj paddle mount\$3 adj (member area))	USPAT	OR	ON	2005/10/24 19:36
L23	1912	(over adj2 hang overlap\$4 overl\$4) same lead same (chip die ic)	USPAT	OR	ON	2005/10/24 19:39
L24	1243	"257"/\$.ccls. and (over adj2 hang overlap\$4 overl\$4) same lead same (chip die ic)	USPAT	OR	ON	2005/10/24 19:41
L25	1288	"257"/\$.ccls. and (over adj2 hang overlap\$4 overl\$4) same lead same (chip die ic)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 19:44
L26	809	"257"/\$.ccls. and (over adj2 hang overlap\$4 overl\$4) with lead same (chip die ic)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 19:44
L27	614	"257"/\$.ccls. and (over adj2 hang overlap\$4 overl\$4) with lead same (chip die ic) and (encapsulant resin epoxy mold\$4)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 19:45
L28	476	"257"/\$.ccls. and (over adj2 hang overlap\$4 overl\$4) with lead with (chip die ic) and (encapsulant resin epoxy mold\$4)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 20:20
L29	153	"438"/\$.ccls. and (over adj2 hang overlap\$4 overl\$4) with lead with (chip die ic) and (encapsulant resin epoxy mold\$4)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 20:08
L30	65	"361"/\$.ccls. and (over adj2 hang overlap\$4 overl\$4) with lead with (chip die ic) and (encapsulant resin epoxy mold\$4)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 20:08
L31	919	"257"/\$.ccls. and (over adj2 hang overlap\$4 overl\$4) same lead same (chip die ic) and (encapsulant resin epoxy mold\$4)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 20:31
L32	59	"257"/\$.ccls. and (over adj2 hang overlap\$4 overl\$4) same lead same (chip die ic) and (encapsulant resin epoxy mold\$4) and MOSFET	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 20:23
L33	7	("4032706" "4124864" "4320412" "4546374" "4916518" "5545846" "5592019"):PN	US-PGPUB; USPAT; USOCR	OR	OFF	2005/10/24 20:21

L34	15	"438"/\$.ccls. and (over adj2 hang overlap\$4 overl\$4) same lead same (chip die ic) and (encapsulant resin epoxy mold\$4) and MOSFET	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 20:23
L35	6	"361"/\$.ccls. and (over adj2 hang overlap\$4 overl\$4) same lead same (chip die ic) and (encapsulant resin epoxy mold\$4) and MOSFET	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 20:24
L36	77	257/735 and (over adj2 hang overlap\$4 overl\$4) same lead and (chip die ic) and (encapsulant resin epoxy mold\$4)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 20:27
L37	65	(over adj2 hang overlap\$4 overl\$4) same lead same (chip die ic) and (encapsulant resin epoxy mold\$4) and MOSFET	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 20:27
L38	498	"257"/\$.ccls. and lead same (chip die ic) and (encapsulant resin epoxy mold\$4) and MOSFET	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 20:43
L39	136	"438"/\$.ccls. and lead same (chip die ic) and (encapsulant resin epoxy mold\$4) and MOSFET	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 20:45
L40	1294	"438"/\$.ccls. and lead same (chip die ic) and (TAB LOC tape adj automat\$3 adj bonding lead adj over adj chip) and wire	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 20:47
L41	923	"438"/\$.ccls. and lead same (chip die ic) and (TAB LOC tape adj automat\$3 adj bonding lead adj over adj chip) same wire	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 20:47
L42	666	"438"/\$.ccls. and lead same (chip die ic) same (TAB LOC tape adj automat\$3 adj bonding lead adj over adj chip) same wire	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 20:47
L43	581	"438"/\$.ccls. and lead same (chip die ic) same (TAB LOC tape adj automat\$3 adj bonding lead adj over adj chip) same wire and (encapsulant epoxy resin mold\$4)	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 20:48
L44	385	"438"/\$.ccls. and lead same (chip die ic) same (TAB LOC tape adj automat\$3 adj bonding lead adj over adj chip) same wire and (encapsulant epoxy resin mold\$4) and (die adj paddle stage flag (mount\$4 adj stage member))	USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2005/10/24 20:49